

Dynamic Group

Hazardous Substance Free (HSF) Management Policy

As a core partner in the global automotive electronics and consumer electronics supply chains, Dynamic Group is deeply aware of the diverse and stringent requirements for high reliability, public safety, and environmental sustainability across various electronic products. We are fully committed to promoting green manufacturing and comprehensively implementing the IECQ QC 080000 Hazardous Substance Process Management (HSPM) system. Through green design at the source, precision supply chain management, and rigorous reliability validation, we deliver Hazardous Substance Free (HSF) printed circuit boards that strictly comply with international environmental regulations and customer requirements.

To implement environmental sustainability and chemical safety management, we solemnly make the following commitments:

1. **Seamless Alignment of Regulations and Technology:** Upon receiving updates on international environmental regulations or notices of substance bans from customers, the company will immediately activate its core response mechanism. We commit to fully completing technical evaluations and reliability testing (such as automotive PPAP changes or consumer high-frequency testing) and entirely introducing eco-friendly alternative materials within 12 months for consumer electronics and within 24 months for automotive electronics.
2. **Establishment of Clear Substitution Timelines:** Regarding existing or potential hazardous substances in our products and manufacturing processes, we will proactively establish specific and traceable substitution schedules for non-toxic alternative chemicals in strict alignment with customers' latest restricted/banned substance requirements (such as IMDS declarations and brand Restricted Substance Lists / RSL).
3. **Guaranteed Allocation of Quantifiable R&D Resources:** We commit to continuously investing approximately 0.5% of our annual revenue into R&D resources and project budgets each year, which are exclusively earmarked for HSF technology research and low-carbon manufacturing equipment upgrades.